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Contact Type: **Socket**

Connector System: **Wire-to-Board, Wire-to-Wire**

Wire Size: **.2 – .5 mm²**

Contact Mating Area Plating Material: **Unplated**

Features

Product Type Features

Connector System	Wire-to-Board, Wire-to-Wire
Sealable	No
Connector & Contact Terminates To	Wire & Cable

Contact Features

Mating Pin Diameter	1.02 mm[.04 in]
Contact Type	Socket
Contact Mating Area Plating Material	Unplated
Contact Current Rating (Max)	5 A

Termination Features

Termination Method to Printed Circuit Board	Through Hole - Solder
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Mechanical Attachment

Connector Mounting Type	Cable Mount (Free-Hanging)
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Dimensions

Wire Size	.2 – .5 mm ²
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Usage Conditions

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Operating Temperature Range	-40 – 105 °C[-40 – 221 °F]
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Operation/Application

Circuit Application	Signal
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Packaging Features

Packaging Method	Box & Tray
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Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Not Yet Reviewed
EU ELV Directive 2000/53/EC	Compliant with Exemptions
China RoHS 2 Directive MIIT Order No 32, 2016	Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUN 2012 (84) SVHC > Threshold: Not Yet Reviewed
Halogen Content	Out of Scope - excluded from Halogen requirements
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulations, TE's information on SVHC in articles for this part number is still based on the European Chemical Agency (ECHA) 'Guidance on requirements for substances in articles' (Version: 2, April 2011), applying the 0.1% weight on weight concentration threshold at the finished product level. TE is aware of the European Court of Justice ruling of September 10th, 2015 also known as O5A (Once An Article Always An Article) stating that, in case of 'complex object', the threshold for a SVHC must be applied to both the product as a whole and simultaneously to each of the articles forming part of its composition. TE has evaluated this ruling based on the new ECHA "Guidance on requirements for substances in articles" (June 2017, version 4.0) and will be updating its statements accordingly.

Documents

Product Drawings

[CONTACT,SKT BODY,EXT PCTAIL](#)

English



CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_2212031-2_B.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2212031-2_B.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_2212031-2_B.3d_stp.zip](#)

English

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Product Specifications

Application Specification

English